60 V, 6.0 A, Low V_{CE(sat)} NPN Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*
- Complementary to NSS60600MZ4

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	60	Vdc
Collector-Base Voltage	V _{CBO}	100	Vdc
Emitter-Base Voltage	V _{EBO}	6.0	Vdc
Collector Current - Continuous	I _C	6.0	Α
Collector Current - Peak	I _{CM}	12.0	Α

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



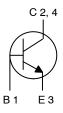
ON Semiconductor®

http://onsemi.com

60 VOLTS, 6.0 AMPS 2.0 WATTS NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 50 m Ω

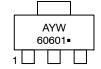


SOT-223 CASE 318E STYLE 1



Schematic

MARKING DIAGRAM



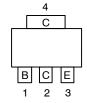
A = Assembly Location

Y = Year W = Work Week

60601 = Specific Device Code

= Pb-Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	155	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 2)	2 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Note 3)	710	mW
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

^{1.} FR-4 @ 7.6 mm², 1 oz. copper traces. 2. FR-4 @ 645 mm², 1 oz. copper traces.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS60601MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSV60601MZ4T1G*	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSS60601MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel
NSV60601MZ4T3G*	SOT-223 (Pb-Free)	4,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP

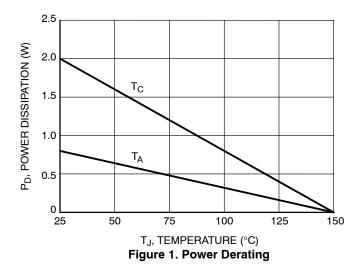
^{3.} Thermal response.

Capable.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Min	Тур	Max	Unit
				•
V _{(BR)CEO}	60	_	_	Vdc
V _{(BR)CBO}	100	-	-	Vdc
V _{(BR)EBO}	6.0	-	_	Vdc
I _{CBO}	=	-	0.1	μAdc
I _{EBO}	_	-	0.1	μAdc
h _{FE}	150 120 100 50	- - - -	- 360 - -	-
V _{CE(sat)}	- - - -	- 0.045 0.085 - -	0.040 0.060 0.100 0.220 0.300	V
V _{BE(sat)}	_	-	0.900	V
V _{BE(on)}	=	-	0.900	V
f _T	100	-	-	MHz
Cibo	=	400	-	pF
Cobo	=	37	-	pF
t _d	-	85	-	ns
t _r	-	115	-	ns
t _s	_	1350	_	ns
3				
	V(BR)CEO V(BR)CBO V(BR)EBO ICBO IEBO VCE(sat) VBE(on) fT Cibo Cobo	V(BR)CEO 60 V(BR)CBO 100 V(BR)EBO 6.0 ICBO - IEBO - NCE(sat) - VBE(sat) - VBE(on) - T 100 Cibo - Cobo - td - td - td - td -	V(BR)CEO 60 - V(BR)CBO 100 - V(BR)EBO 6.0 - ICBO - - IEBO - - NFE 150 - 120 - - 100 - - NCE(sat) - - NBE(sat) - - VBE(on) - - Tobo - 400 Cobo - 37	V(BR)CEO 60 - - V(BR)CBO 100 - - V(BR)EBO 6.0 - - ICBO - - 0.1 IEBO - - 0.1 hFE 150 - - 120 - 360 100 - - VCE(sat) - - - 0.045 0.060 - 0.220 - - 0.300 VBE(sat) - - 0.900 VBE(on) - - 0.900 fT 100 - - Cobo - 37 - td - 85 - td - 115 -

^{4.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.



TYPICAL CHARACTERISTICS

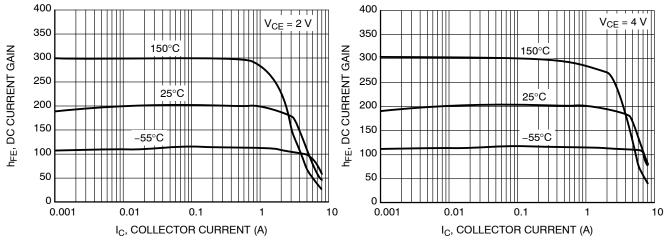


Figure 2. DC Current Gain

Figure 3. DC Current Gain

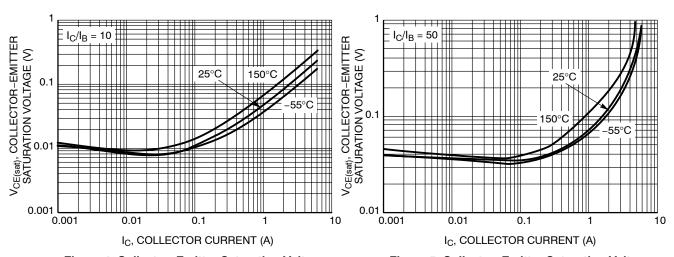


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage

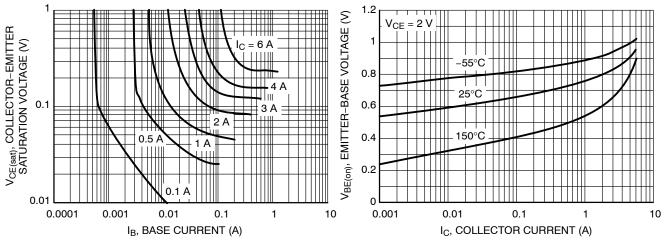
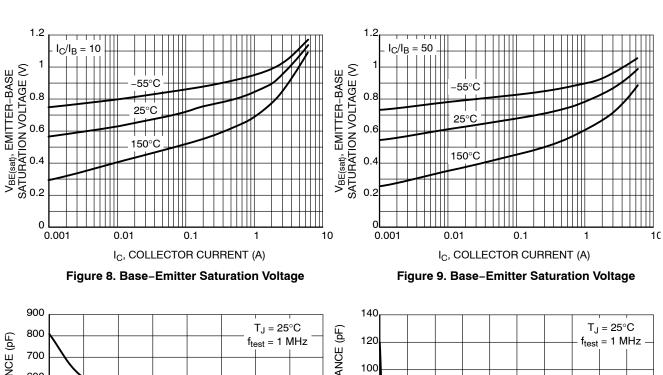
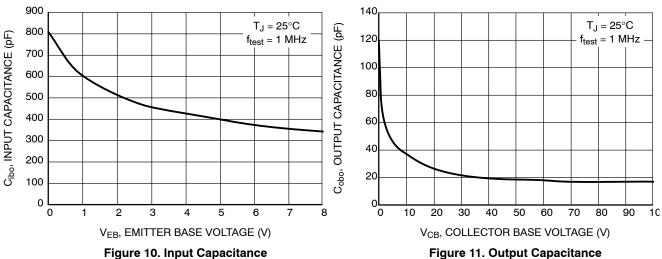


Figure 6. Collector Saturation Region

Figure 7. V_{BE(on)} Voltage

TYPICAL CHARACTERISTICS





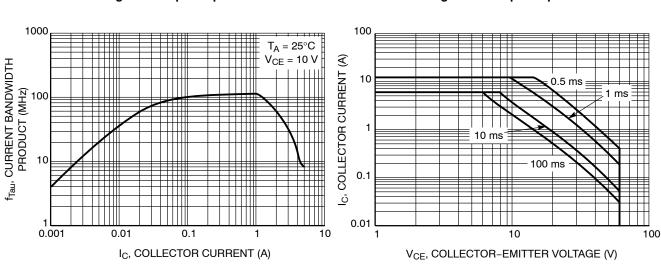
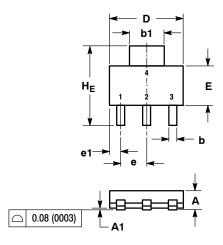
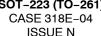


Figure 12. Current-Gain Bandwidth Product Figure 13. Safe Operating Area

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04





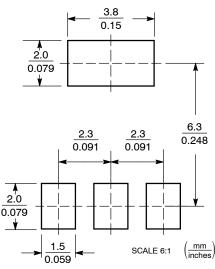
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	_	10°	0°	_	10°

STYLE 1: PIN 1. BASE

- COLLECTOR EMITTER 2.
- COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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